300mm Fully-Automatic Multifunction Wafer Mounter





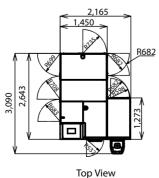
## Outline

- Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions:
- · UV irradiation to BG Tape · Alignment
- · Wafer mounting · BG Tape peeling
- Ability to operate in-line with DISCO Corporation's DFG8000 series back grinder or DGP8000 series grinder/polisher.
- Corresponds to DBG<sup>™</sup> process.
- Prevents wafer damage by reducing wafer handling frequency down to 4 times "stand-alone," and 2 times "in-line."

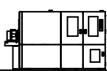
Options ·Host Communication Function (Communication Format : Conforms to SECS-I and HSMS/Software : Conforms to GEM) ·Vision System (Wafer ID Reader & Barcode Attachment System) ·Dicing Tape In-line Pre-cutting •DBG<sup>™</sup> Process Compatibility ·In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series

Suitable Tapes ·Dicing tape : Adwill D series, G series ·Dicing die bonding tape : Adwill LE Tape

## External View



Front View



**Right Side View** 



## **INTEC** LINTEC Corporation Linking your dreams

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## Facility

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Power Supply	Voltage	: AC200 (±10%)
	Frequency	: 50/60Hz
	Phase	: 3 phase
	Power consumption	: 8.0kW (200VAC)
Air Supply	Air pressure	: 0.6-0.8MPa
	Air consumption	:>800L/min (ANR)
Vacuum Supply	Vacuum pressure	:>-80kPa
Applicable Wafer Size	200mm, 300mm	
Size	Width : 2,165mm	
	Depth : 3,090mm	A MARKED A
	Height : 1,800mm	
	(excluding the signal t	ower and protruding parts)
Weight	3,100kg	
UPH	45wafers/hour	
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will give you the Advantage

The above pacity is based on following conditions ("stand alone"):

- Wafer : 300mm diameter non-polished mirror wafer
- **Ring frame** : for 300mm wafer

Dicing tape : G-18 from LINTEC

Back grinding tape : E-8180HR from LINTEC

